

ADHESIVE FILM FOR WAFER PROCESSING

ABSTRACT OF THE DISCLOSURE

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Disclosed is an adhesive film for wafer processing including a multilayer substrate comprising an upper substrate layer and a lower substrate layer, a first adhesive layer disposed on the upper substrate layer and a second adhesive layer disposed between the upper substrate layer and the lower substrate layer, and the second adhesive layer may be formed of a second adhesive composition comprising an adhesive resin and core-shell nanoparticles, to have an excellent surface protection effect and excellent control for adhesive layer flowability.

[Fig. 1]